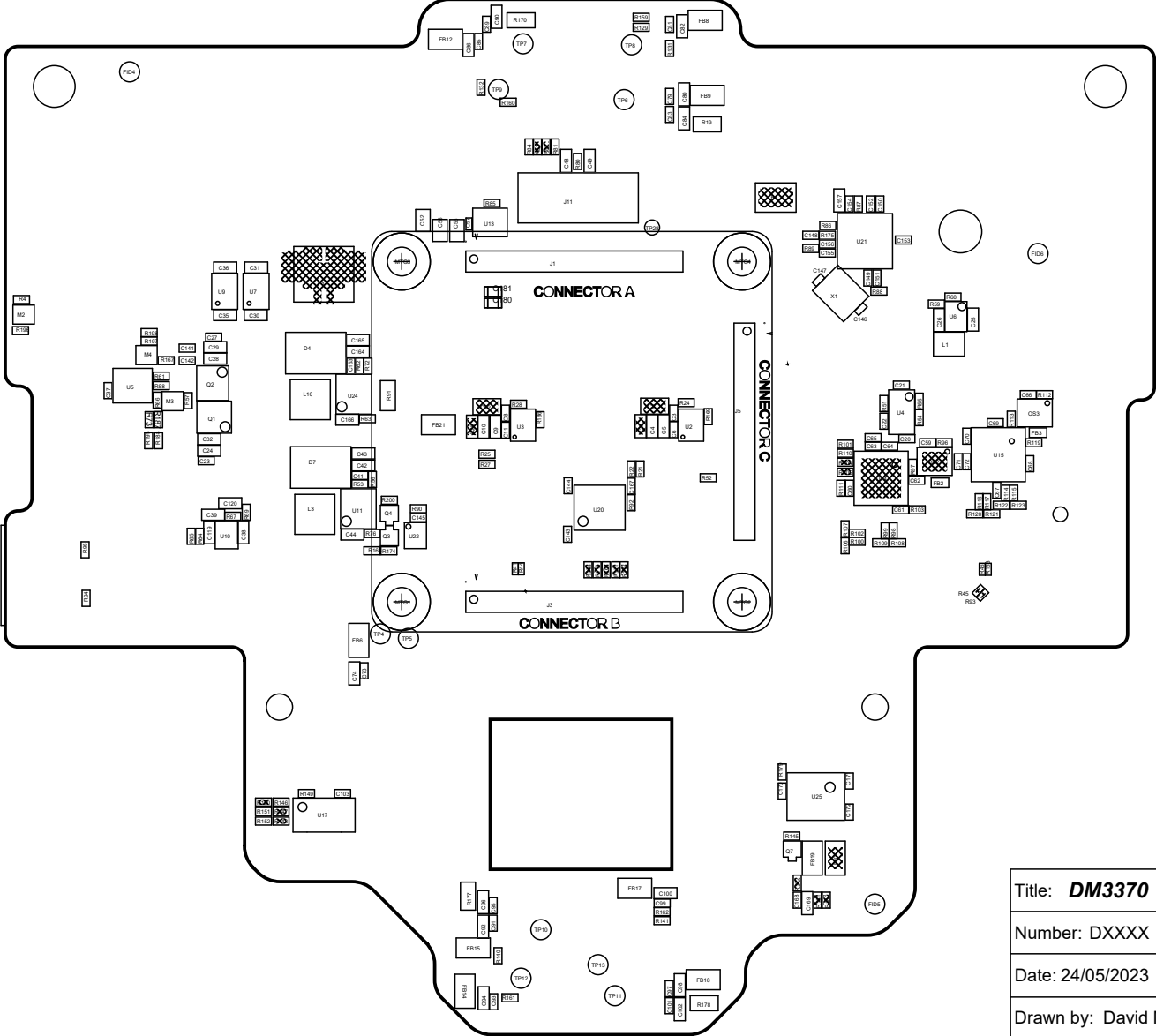


ASSEMBLY NOTES:

Assembly shall conform to IPC-A-610 Class 2.
Assembly shall conform with RoHS Directive 2011/65/EU.
Components shall be placed according to the associated CPL and BOM documents.
Lead-free SAC305 solder shall be used.
Reflow profile shall comply with J-STD-20C Lead-Free Reflow Profile.
BGA components shall be 100% checked with x-ray for solder bridges after reflow.
Finished assemblies shall be removed from panel prior to delivery.

[Variant: Production] View from Top side (Scale 1.5:1)



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A

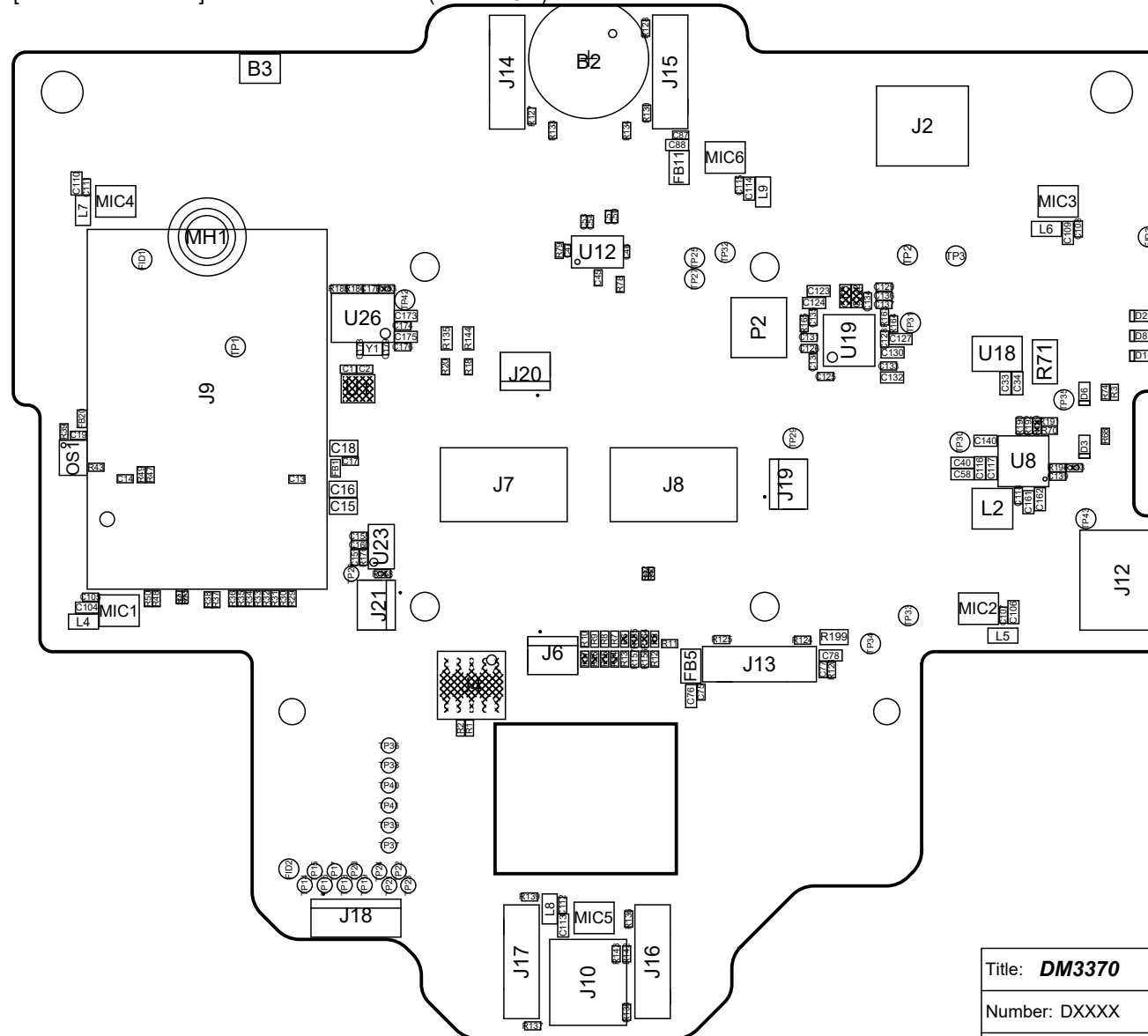
B


C

D

E

[Variant: Production] View from Bottom side (Scale 1.5:1)



Title: DM3370		
Number: DXXXX	Revision: R5M2E5	
Date: 24/05/2023	Sheet: 2 of 2	PROPRIETARY AND CONFIDENTIAL
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